Electronic Patent Application Fee Transmittal							
Application Number:	10537959						
Filing Date:	07-Jun-2005						
Title of Invention:	Thermoplastic polyimide resin film, multilayer body and method for manufacturing printed wiring board composed of same						
First Named Inventor/Applicant Name:	Shigeru Tanaka						
Filer:	Dariush G. Adli/Yaning Liu						
Attorney Docket Number:	81844.0036						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 3 months with \$0 paid		1253	1	1110	1110		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			1110